

Company :

Company Name :

Nature Of Business :

Designation :

Tentative Job Location :

LAM Research

LAM Research

Core

Senior Mechanical Engineer

Bangalore

Description :

- Design of components and subassemblies for semiconductor processing equipment, with specific focus on process chambers, gas/liquid distribution systems, packaging of electronics and high voltage power distribution systems
- Coordinate design activities with computational modeling to drive robust design decisions in a fast-moving environment
- Collaborate with counterparts in Lam Research locations to obtain requirements and validate design against the requirements

Eligibility :

Program	AE	BSBE	CE	CHE	CSE	EE	ES	ME	MSE	PHY	CHM	MTH	ECO	DES	IME	CGS	HSS	EEM	MSP	NET	PSE	Stats
BT	No	No	No	No	No	No	--	No	No	--	--	--	--	--	--	--	--	--	--	--	--	--
BS	--	--	--	--	--	--	No	--	--	No	No	No	No	--	--	--	--	--	--	--	--	--
MT	Yes	No	No	No	No	No	No	Yes	No	--	--	--	--	--	No	--	--	No	No	No	No	--
DoubleMajor	No	No	No	No	No	No	--	No	No	No	No	No	No	--	--	--	--	--	--	--	--	--
dual	Yes	No	No	No	No	No	No	Yes	No	No	No	No	No	--	--	--	--	--	--	--	--	--
dualB	Yes	No	No	No	No	No	--	Yes	No	No	No	No	No	--	No	--	--	No	--	No	No	--
dualC	Yes	No	No	No	No	No	No	Yes	No	No	No	No	No	No	No	--	--	--	--	--	--	--
Mdes	--	--	--	--	--	--	--	--	--	--	--	--	--	No	--	--	--	--	--	--	--	--
MBA	--	--	--	--	--	--	--	--	--	--	--	--	--	--	No	--	--	--	--	--	--	--
Phd	No	No	No	No	No	No	No	No	No	No	No	No	No	No	No	No	No	No	No	No	No	No
MSc	--	--	--	--	--	--	--	--	--	No	No	No	--	--	--	--	--	--	--	--	--	No
MSR	Yes	No	No	No	No	No	--	Yes	No	--	--	--	--	--	--	No	--	--	--	--	No	--

Cost to Company :

Package Details :

- M.tech / MS Compensation : Rs. 17,80,208/- Per Annum
- Masters Dual Compensation : Rs. 18,44,623/- Per Annum

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Bond :

CPI CutOff :

Medical Requirments :

Resume Shortlist :

Aptitude Test:

Aptitude Test

Duration:

Group Discussion:

Technical Test:

Technical Test

Duration:

Technical Interview:

Technical Interview

Duration:

Number of Techincal Interview Rounds:

HR Interview:

Additional Information:

False

0.0

False

True

45

False

True

45

True

N/A

2

False

7 CGPA & Above, Salary Bifurcation will be shared with offered candidates, refer to the mail for eligible branches